

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## BTCxxxN-MS

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Product specification

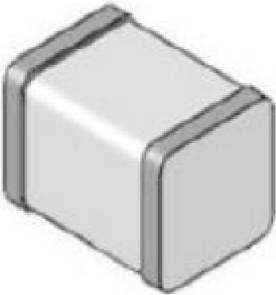
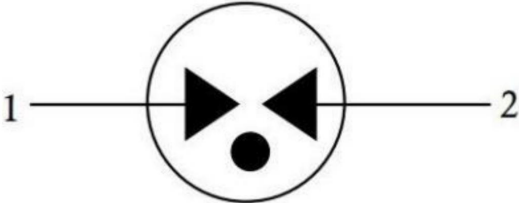
**Features**

- High insulation resistance: 1GΩ@100V
- Size design: 4.5\*3.2\*2.7mm
- Surge capability: 2KA@8/20us
- Very low capacitance:0.5pF@1MHz,0V

**Applications**

- AC Power

**Reference News**

PACKAGE OUTLINE	Schematic Symbol
	
1812	

**Electrical characteristics(T=25℃)**

Model Name	DC spark-over Voltage	Tolerance of Vs	Max . Impulse Breakdown Voltage	Discharge Current (8/20us)	Minimum Insulation Resistance		Max. Capacitance 1 MHz
	100V/S		1KV/us	10 times			
	V	%	V	KA	Test Voltage DC(V)	(GΩ)	(Pf)
BTC075N-MS	75	±30	600	2	50	1	<0.5
BTC900N-MS	90	±30	600	2	50	1	<0.5
BTC151N-MS	150	±20	600	2	100	1	<0.5
BTC231N-MS	230	±20	800	2	100	1	<0.5
BTC301N-MS	300	±20	850	2	100	1	<0.5
BTC351N-MS	350	±20	950	2	100	1	<0.5
BTC401N-MS	400	±20	1000	2	100	1	<0.5
BTC471N-MS	470	±20	1 100	2	100	1	<0.5
BTC601N-MS	600	±20	1300	2	100	1	<0.5

**Notes:**

- 1) At delivery AQL 0.65 level II ISO 2828. 1-2003
- 2) In ionized mode
- 3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Environmental Reliability Characteristics

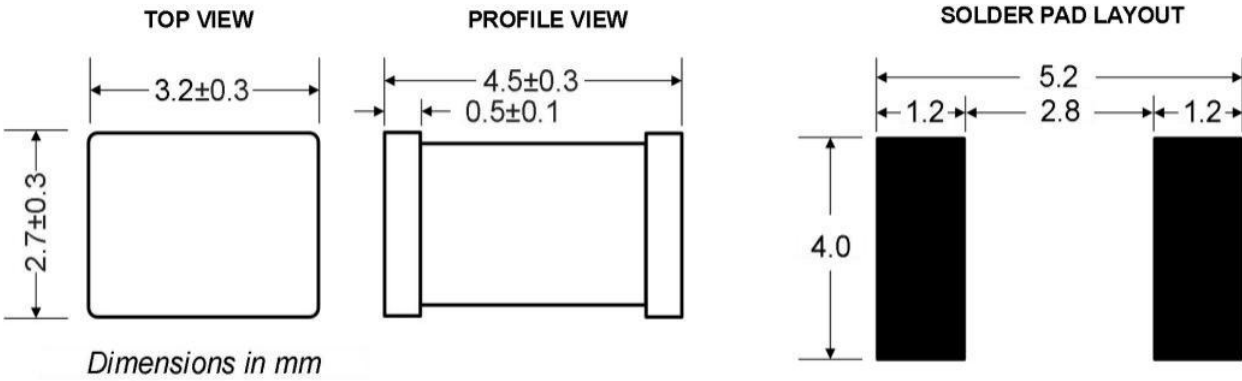
Testing items	Technical standards
High Temperature Storage Test	Temperature: 90℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45mins
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering: 10s, 1time

Note:Up-screen program can be specified by customer's request via contacting MSKSEMI service

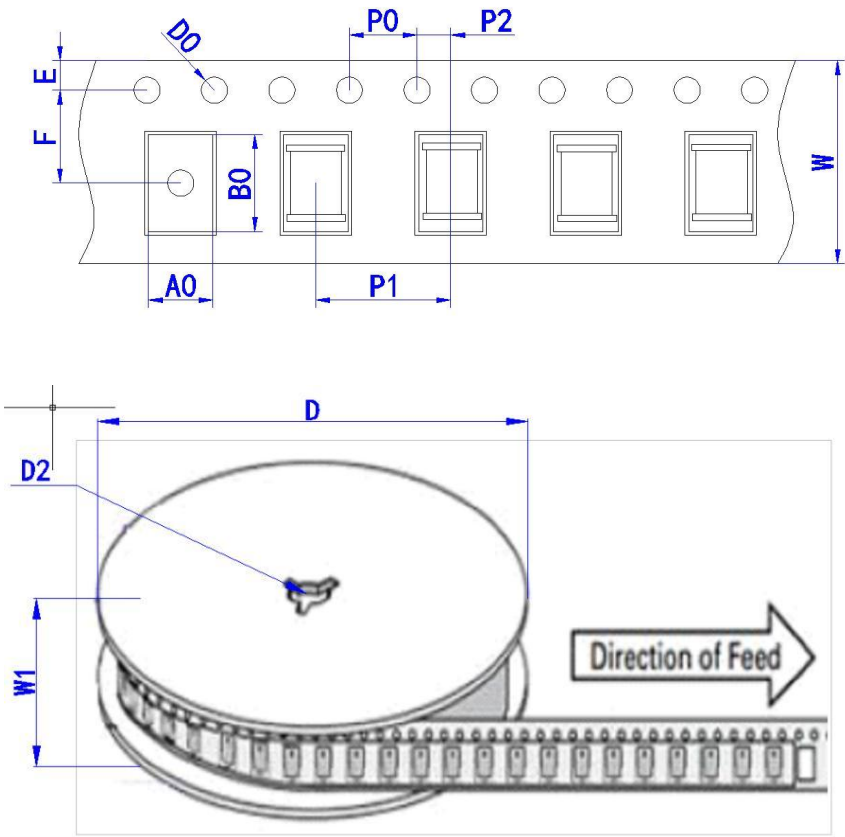
Soldering parameters

Solderability	SolderPotTemperature	245℃±5℃
	SolderDwellTime	4-6seconds

Package mechanical data



Tape & reel specification



Sym .	Dimensions( mm)
A0	3.90±0.20
B0	4.90±0.20
D0	φ 1.50±0. 10
E	1.75±0.20
F	5.50±0.20
P1	8.00±0.20
P0	4.00±0.20
P2	2.00±0.20
W	12.00±0.30
W1	16.80±2.00
D	φ333±4.00
D2	φ 13.±0.2

Marking & Packeging Information

Marking	Packaging	Reel Size
/	2500/Reel	330mm

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